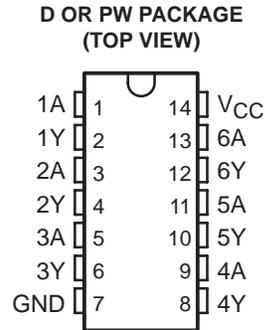


SN74AHCT14Q-Q1 HEX SCHMITT-TRIGGER INVERTER

SGDS023A – FEBRUARY 2002 – REVISED APRIL 2008

- Qualified for Automotive Applications
- EPIC™ (Enhanced-Performance Implanted CMOS) Process
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)



description

The SN74AHCT14Q contains six independent inverters. This device performs the Boolean function $Y = \bar{A}$.

Each circuit functions as an independent inverter, but because of the Schmitt action, the inverters have different input threshold levels for positive-going (V_{T+}) and for negative-going (V_{T-}) signals.

ORDERING INFORMATION†

T _A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – D	Tape and reel	SN74AHCT14QDRQ1	AHCT14Q
	TSSOP – PW	Tape and reel	SN74AHCT14QPWRQ1	HB14Q

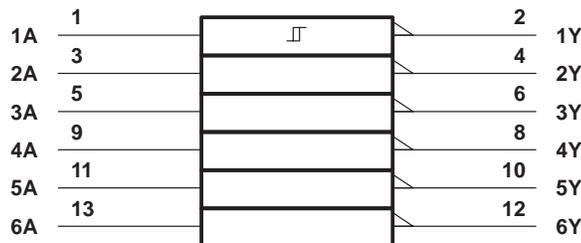
† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V _{T+} Positive-going input threshold voltage		4.5 V	0.9		1.9	0.9	1.9	V
		5.5 V	1		2.1	1	2.1	
V _{T-} Negative-going input threshold voltage		4.5 V	0.5		1.5	0.5	1.5	V
		5.5 V	0.6		1.7	0.6	1.7	
ΔV _T Hysteresis (V _{T+} - V _{T-})		4.5 V	0.4		1.4	0.4	1.4	V
		5.5 V	0.4		1.5	0.4	1.5	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		V
	I _{OH} = -8 mA	4.5 V	3.94			3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1		0.1	V
	I _{OL} = 8 mA	4.5 V			0.36		0.44	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V				±0.1	±1	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V				2	20	μA
ΔI _{CC} [†]	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5	mA
C _i	V _I = V _{CC} or GND	5 V		2	10			pF

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

**switching characteristics over recommended operating free-air temperature range
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
t _{PLH}	A	Y	C _L = 15 pF		4	7	1	8	ns
t _{PHL}					4	7	1	8	
t _{PLH}	A	Y	C _L = 50 pF		5.5	8	1	9	ns
t _{PHL}					5.5	8	1	9	

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)} Quiet output, maximum dynamic V _{OL}		0.9		V
V _{OL(V)} Quiet output, minimum dynamic V _{OL}		-0.7		V
V _{OH(V)} Quiet output, minimum dynamic V _{OH}		4.3		V
V _{IH(D)} High-level dynamic input voltage		2.1		V
V _{IL(D)} Low-level dynamic input voltage			0.5	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

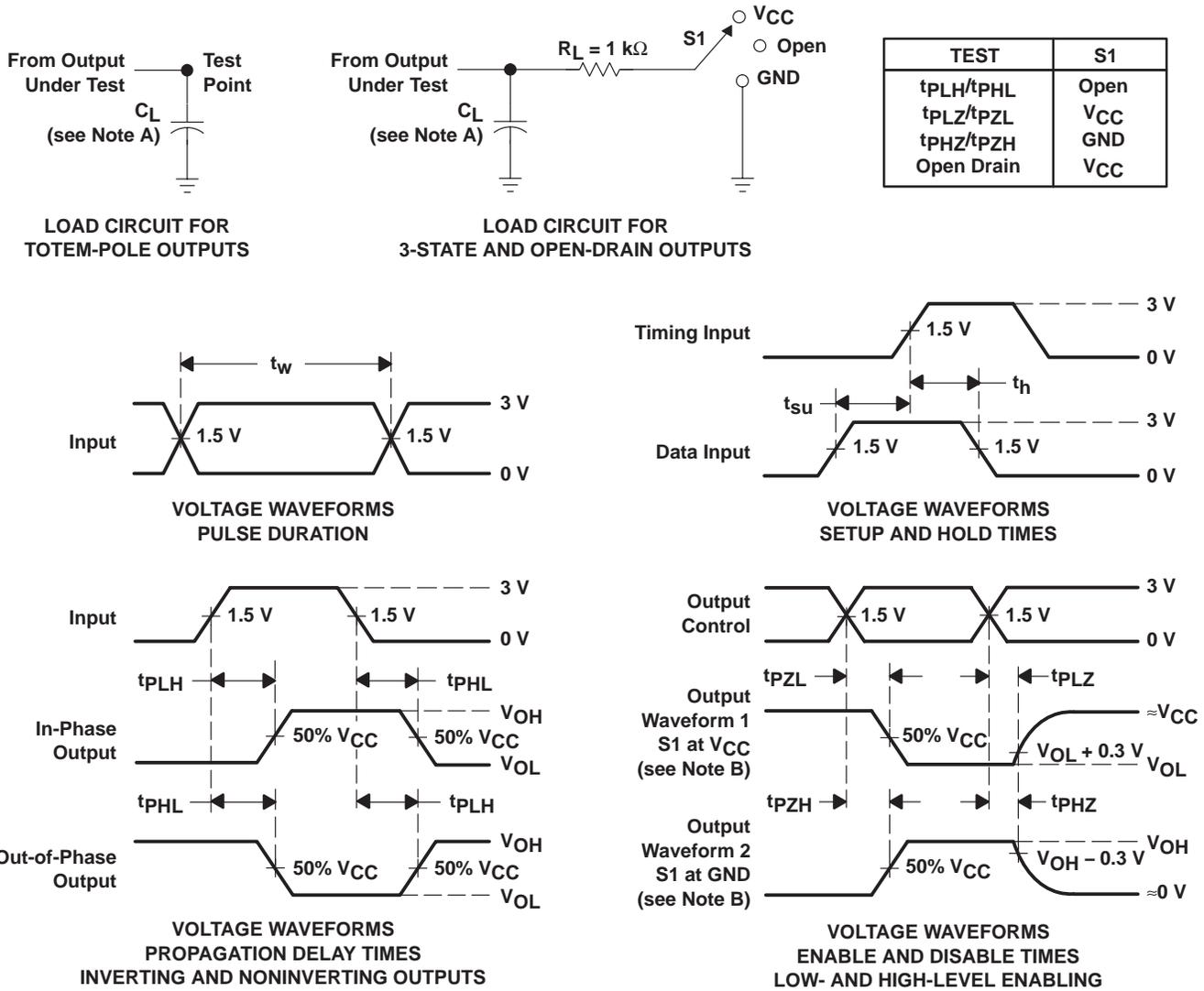
PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load, f = 1 MHz	12	pF



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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHCT14QDRG4Q1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT14Q	Samples
SN74AHCT14QDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT14Q	Samples
SN74AHCT14QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB14Q	Samples
SN74AHCT14QPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB14Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

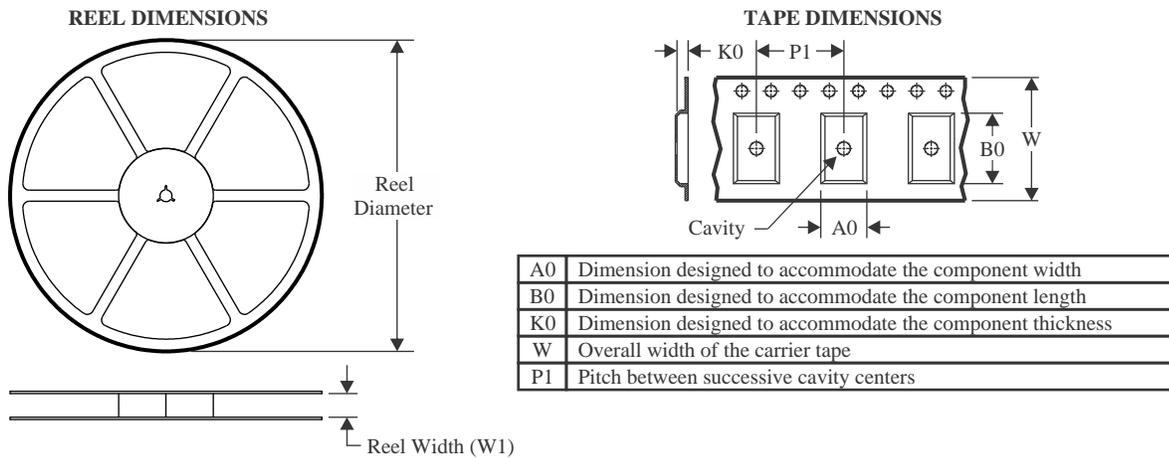
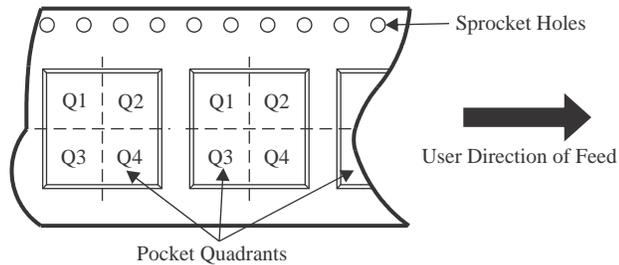
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT14QPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT14QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

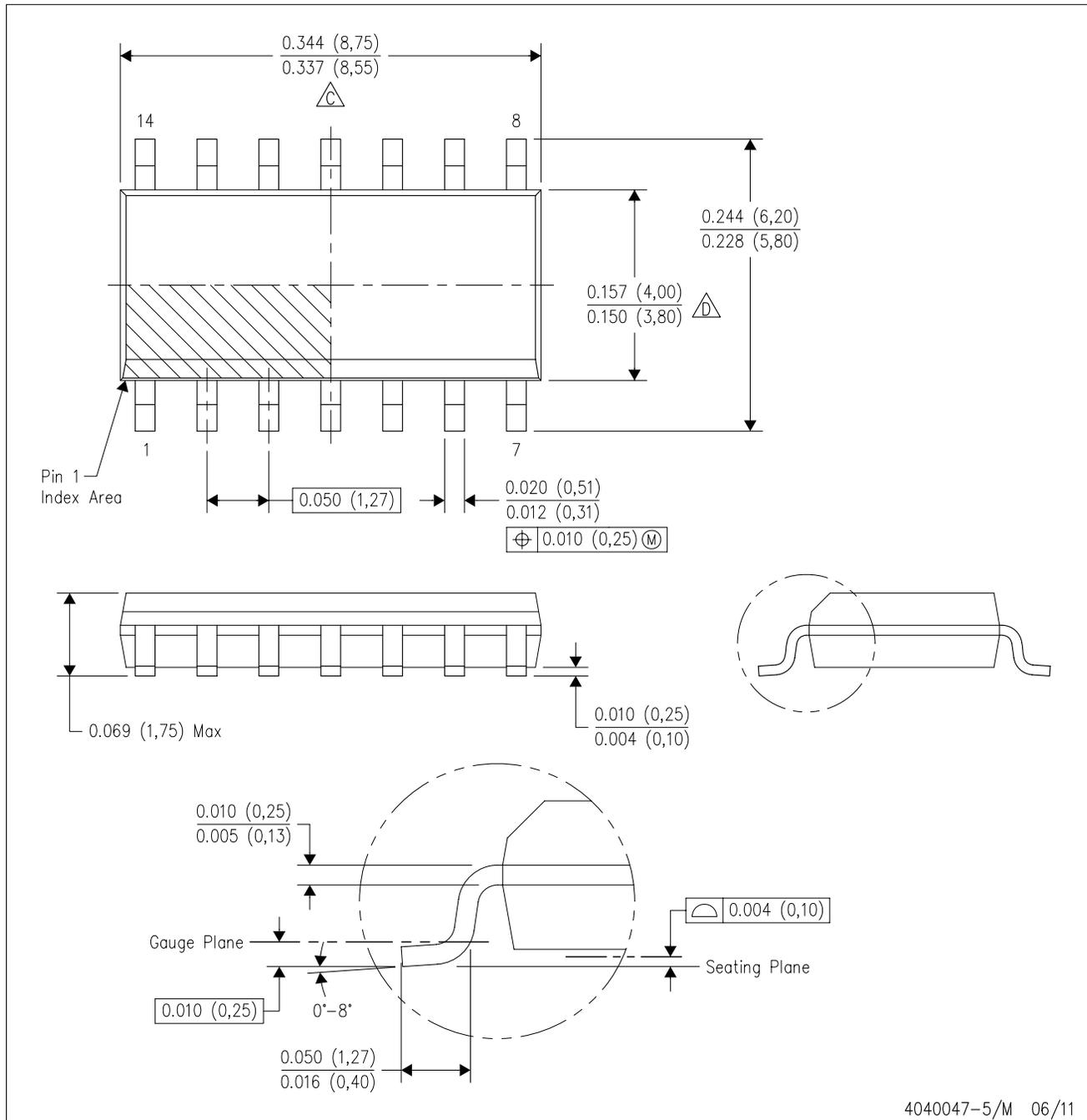


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT14QPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHCT14QPWRQ1	TSSOP	PW	14	2000	356.0	356.0	35.0

D (R-PDSO-G14)

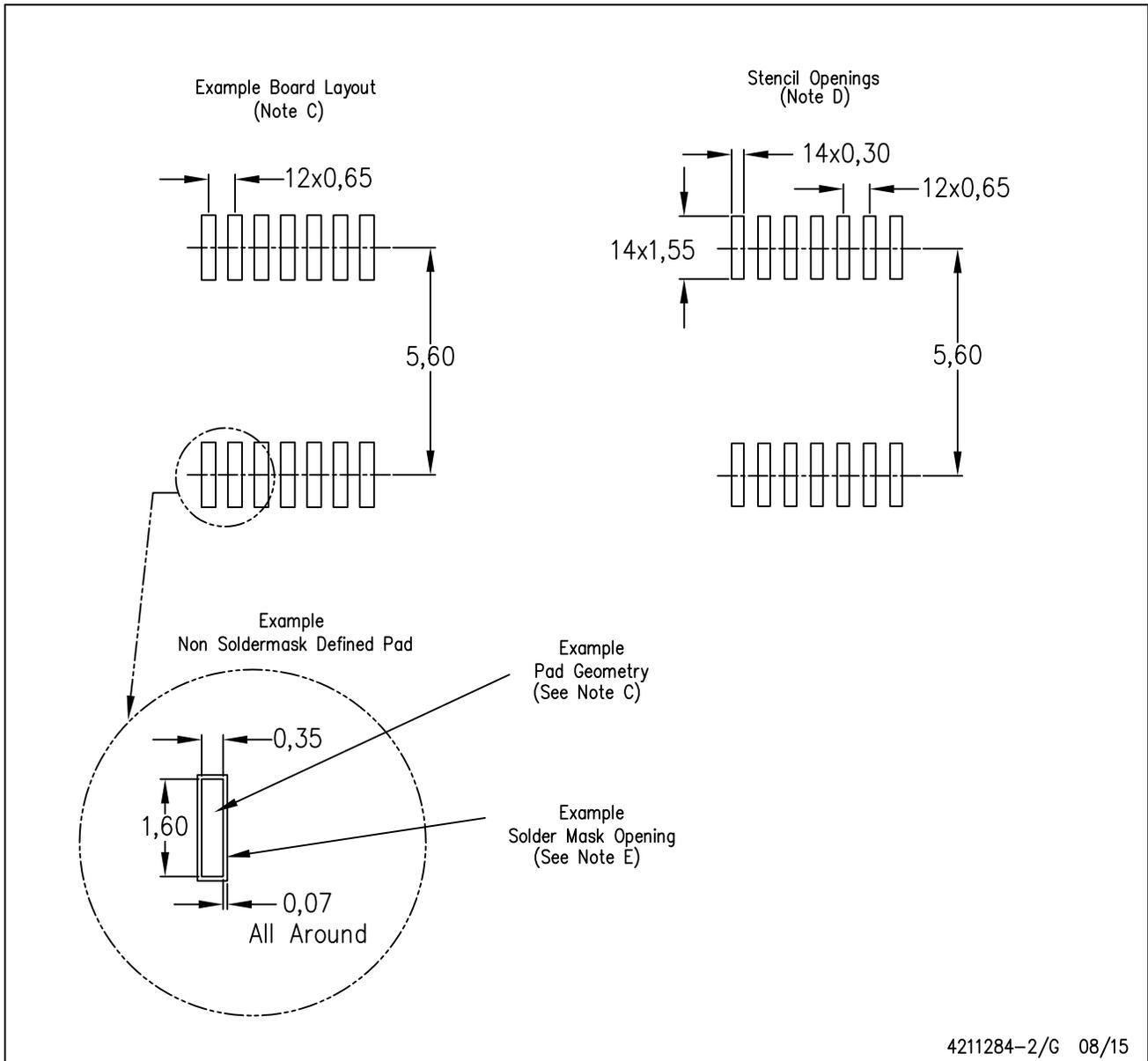
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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